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(54) Title: DISPLAY DEVICE AND ELECTRONICS APPARATUS

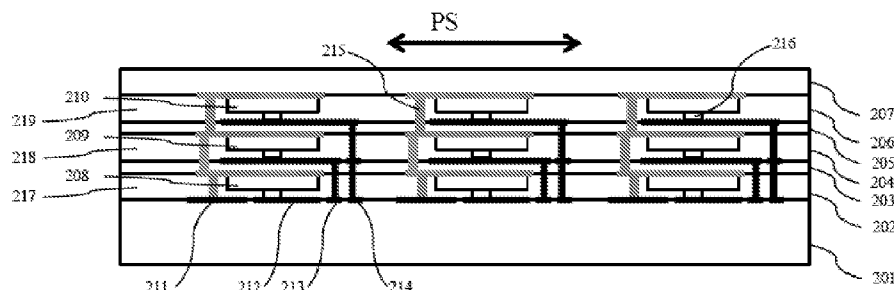


FIG. 4

(57) Abstract: A display device and an electronics apparatus, the display device comprises: a display substrate (201, 301); and at least two stacked layers (202, 204, 206; 302, 304, 306) on the display substrate (201, 301), wherein each stacked layer (202, 204, 206; 302, 304, 306) includes one micro-LED array (208, 209, 210; 308, 309, 310). It may simplify the manufacture of a display device, compared to a prior art display device with similar display resolution.

DISPLAY DEVICE AND ELECTRONICS APPARATUS

FIELD OF THE INVENTION

The present invention relates to the field of micro-LED display device, and more specifically, to a display device and an electronics apparatus.

BACKGROUND OF THE INVENTION

The micro-LED technology refers to the LED array of small size integrated on a substrate with high density. Currently, the micro-LED technology is starting development, and it is expected in the industry that a high-quality micro-LED product comes into the market. High-quality micro-LEDs will have a deep affection on the conventional display products such as LCD/OLED that have already been put into the market.

A micro-LED display device is a device with micro-LED array. Currently, a high quality micro-LED display device has encountered manufacturing difficulty in high resolution display.

Typically, the red, green and blue (RGB) sub-pixels within a pixel is horizontally positioned and laid-out in a display substrate in the prior art, which limited the highest display resolution. As shown in Fig. 1, the pixel size PS is determined by the sizes of a group of RGB sub-pixels (the sum of three sub-pixels).

Figs. 2-3 show the procedure of transferring red, green and blue (RGB) sub-pixel arrays to a display substrate, respectively.

As shown in Fig. 2, a red sub-pixel array is first transferred to the display substrate 101. Then, the green sub-pixel array on a carrier substrate 102 is transferred to the display substrate 101. The transfer of the green sub-pixel array may have negative impact on the red sub-pixel array which has already been on the display substrate 101.

As shown in Fig. 3, the blue sub-pixel array on a carrier substrate 103 is transferred to the display substrate 101. Likewise, the transfer of the blue sub-pixel array may have negative impact on the red and green sub-pixel arrays which has already been on the display substrate 101.

Furthermore, in the prior art, arrays of massive RGB micro-LEDs are, color by color, transferred onto a same display surface. This may dramatically increase the manufacturing

complicity. The manufacturing difficulty may also be increased due to surface topography changes after partial color transfer(s). Consequently, this may become a bottle-neck of yield and quality at a decent fabrication cost.

Therefore, there is a demand in the art that a new solution for a display device shall be
5 proposed to address at least one of the problems in the prior art.

SUMMARY OF THE INVENTION

One object of this invention is to provide a new technical solution for a display device.

According to a first aspect of the present invention, there is provided a display device,
comprising: a display substrate; and at least two stacked layers on the display substrate, wherein
10 each stacked layer includes one micro-LED array.

Optionally or alternatively, the stacked layers include, in sequence from the display
substrate, a first stacked layer, a second stacked layer and a third stacked layer, and wherein the
micro-LED array in the first stacked layer is a red micro-LED array, the micro-LED array in the
second stacked layer is a green micro-LED array, and the micro-LED array in the third stacked
15 layer is a blue micro-LED array.

Optionally or alternatively, micro-LEDs in different stacked layers are not overlapped in
vertical direction.

Optionally or alternatively, micro-LEDs in different stacked layers are overlapped at
least partially in vertical direction.

20 Optionally or alternatively, a dielectric layer is placed between two adjacent stacked
layers.

Optionally or alternatively, micro-LEDs in each stacked layers are transparent.

Optionally or alternatively, a transparent filler is placed between micro-LEDs in each
stacked layer.

25 Optionally or alternatively, micro-LEDs in the stacked layers are connected with the
display substrate through transparent electrodes.

Optionally or alternatively, electrodes of micro-LEDs in the stacked layers are led out to
the display substrate through vias.

According to a second aspect of the present invention, there is provided an electronics apparatus comprising a display device according to the present invention.

According to an embodiment of this invention, the present invention may simplify the manufacture of a display device, compared to a prior art display device with similar display
5 resolution.

Further features of the present invention and advantages thereof will become apparent from the following detailed description of exemplary embodiments according to the present invention with reference to the attached drawings.

BRIEF DISCRIPTION OF THE DRAWINGS

10 The accompanying drawings, which are incorporated in and constitute a part of the specification, illustrate embodiments of the invention and, together with the description thereof, serve to explain the principles of the invention.

Fig. 1 is a schematic diagram showing a display device of the prior art.

Figs. 2-3 is a schematic diagram showing the prior art procedure of transferring RGB
15 sub-pixel arrays onto a same display substrate.

Fig. 4 is a schematic diagram showing a display device according to an embodiment of this invention.

Fig. 5 is a schematic diagram showing a display device according to another embodiment of this invention.

DETAILED DESCRIPTION OF THE EMBODIMENTS

20 Various exemplary embodiments of the present invention will now be described in detail with reference to the drawings. It should be noted that the relative arrangement of the components and steps, the numerical expressions, and numerical values set forth in these embodiments do not limit the scope of the present invention unless it is specifically stated
25 otherwise.

The following description of at least one exemplary embodiment is merely illustrative in nature and is in no way intended to limit the invention, its application, or uses.

Techniques, methods and apparatus as known by one of ordinary skill in the relevant art may not be discussed in detail but are intended to be part of the specification where appropriate.

In all of the examples illustrated and discussed herein, any specific values should be
5 interpreted to be illustrative only and non-limiting. Thus, other examples of the exemplary embodiments could have different values.

Notice that similar reference numerals and letters refer to similar items in the following figures, and thus once an item is defined in one figure, it is possible that it need not be further discussed for following figures.

10 In the embodiment of this invention, it is proposed to stack RGB sub-pixels in different layers in the vertical direction. In this way, the display resolution may be increased, or it may simplify the manufacturing processes compared to a prior art display device with similar display resolution.

The embodiments or examples will be described with reference to Figs. 4-5.

15 Fig. 4 is a schematic diagram showing a display device according to an embodiment of this invention.

As shown in Fig. 4, the display device comprises a display substrate 201 and at least two stacked layers 202, 204, 206 on the display substrate. Each stacked layer 202, 204, 206 includes one micro-LED array.

20 Although Fig. 4 shows three layers 202, 204, 206, it will be understood by a person skilled in the art that there can be two layers or more than three layers. The micro-LED array in each layer can be of the same color or different color.

Since the micro-LEDs of sub-pixels are placed on different layers. In each layer, the distance between two micro-LEDs is enlarged compared with the prior art solution.
25 Consequently, the manufacture may be easier compared with the prior art solution of putting all micro-LEDs on the same surface.

As shown in Fig. 4, in an example, the stacked layers include, in sequence from the display substrate 201, a first stacked layer 202, a second stacked layer 204 and a third stacked layer 206. The micro-LED array 208 in the first stacked layer 202 is a red

micro-LED array. The micro-LED array 209 in the second stacked layer 204 is a green micro-LED array. The micro-LED array 210 in the third stacked layer 206 is a blue micro-LED array.

In such an arrangement, the influence between different layers of micro-LEDs will be reduced. For example, because the blue color has the highest frequency or has the highest energy among the three colors, it may excite fluorescent light on the other color micro-LEDs if it is placed beneath them. By the arrangement this invention, it reduces this fluorescence excitation.

In the embodiment of Fig. 4, the micro-LEDs 208, 209, 210 in different stacked layers 202, 204, 206 are overlapped in the vertical direction. It can be understood by a person skilled in the art that they can partially be overlapped in the vertical direction.

By such an arrangement, the pixel size may be reduced significantly compared with the prior art arrangement of placing all color micro-LEDs in the same display substrate.

In Fig. 4, a dielectric layer 203, 205 is placed between two adjacent stacked layers 202, 204, 206 to isolate them. The dielectric layers 203, 205 are transparent, for example.

The micro-LEDs 209, 210 are transparent. In an example, the micro-LEDs 208, 209, 210 in each stacked layers are transparent.

A transparent filler 217, 218, 219 is placed between micro-LEDs 208, 209, 210 in each stacked layer 202, 204, 206.

The micro-LEDs 208, 209, 210 in the stacked layers 202, 204, 206 are connected with the display substrate 201 through transparent electrodes 211, 212, 213, 214. For example, the electrodes 211 may be cathode electrodes. The electrodes 212, 213, 214 may be anode electrodes for micro-LEDs in different layers.

The electrodes of micro-LEDs 208, 209, 210 in the stacked layers 202, 204, 206 are led out to the display substrate 201 through vias 215, for example.

In this embodiment, the micro-LEDs of red, green and blue can be stacked vertically to form a RGB pixel. The micro-LEDs micro-LED can include III-V inorganic semiconductors.

For example, each color micro-LED array is transferred onto a planar surface

through micro-bumps 216 on anode electrodes 212, 213, 214. After each transfer, a planarization is performed on the micro-LED array by filling/coating transparent filler 217, 218, 219 such as polymer or resist and etching-back or polishing. A transparent cover 207 can be placed on the top of the stacked micro-LED layers to protect the micro-LEDs.

5 Since the micro-LEDs of different colors can be placed in different layers, the impact of a subsequent transfer on the micro-LEDs which have already been placed on the display substrate will be reduced. For example, the red micro-LEDs are first transferred on the display substrate. Because the red and green micro-LEDs are in different layers, the impact on the red micro-LEDs by the transfer of the green micro-LEDs will be lowered. The
10 same situation will be applied to the blue micro-LEDs.

Alternatively, the micro-LED array of each color can be placed in a pre-fabricated layer, such as a tape. In this manner, the manufacture process may be simplified. For example, the pre-fabricated layer can be made at a first position and is transported to a display manufacturing factory to be assembled into a display device.

15 Fig. 5 is a schematic diagram showing a display device according to another embodiment of this invention.

In Fig. 5, the micro-LEDs 308, 309, 310 in different stacked layers 302, 304, 306 are not overlapped in vertical direction. Repetitive description with Fig. 1 will be omitted.

As shown in Fig. 5, three layers 302, 304, 306 are stacked on the display substrate
20 301. Each layer includes a micro-LED array 308, 309, 310. A transparent filler 317, 318, 319 is filled between two micro-LEDs in each layer. The micro-LEDs are placed on micro-bumps 316 which are connected with anode electrodes 312, 313, 314. The cathodes of the micro-LEDs are connected with the cathodes electrode 311. The electrodes 311, 312, 313, 314 can be connected to the display substrate 301 through vias 315. A transparent cover
25 307 can be placed on the top of the stacked micro-LED layers to protect the micro-LEDs.

In Fig. 5, dielectric layer 303, 305 are placed between layers 302, 304, 306 for isolation. These dielectric layers 303, 305 can be omitted since the micro-LEDs in different layers are not overlapped.

In still another embodiment, the display device according to any embodiment of this invention can be used in an electronics apparatus such as a mobile phone, a pad, a laptop and headset and so on.

Although some specific embodiments of the present invention have been
5 demonstrated in detail with examples, it should be understood by a person skilled in the art that the above examples are only intended to be illustrative but not to limit the scope of the present invention.

CLAIMS

What is claimed is:

1. A display device, comprising:

a display substrate; and

5 at least two stacked layers on the display substrate, wherein each stacked layer includes one micro-LED array.

2. The display device according to claim 1, wherein the stacked layers include, in sequence from the display substrate, a first stacked layer, a second stacked layer and a third
10 stacked layer, and

wherein the micro-LED array in the first stacked layer is a red micro-LED array, the micro-LED array in the second stacked layer is a green micro-LED array, and the micro-LED array in the third stacked layer is a blue micro-LED array.

15 3. The display device according to claim 1 or 2, wherein micro-LEDs in different stacked layers are not overlapped in vertical direction.

4. The display device according to claim 1 or 2, wherein micro-LEDs in different stacked layers are overlapped at least partially in vertical direction.

20

5. The display device according to any of claims 1-4, wherein a dielectric layer is placed between two adjacent stacked layers.

6. The display device according to any of claims 1-5, wherein micro-LEDs in each
25 stacked layers are transparent.

7. The display device according to any of claims 1-6, wherein a transparent filler is placed between micro-LEDs in each stacked layer.

8. The display device according to any of claims 1-7, wherein micro-LEDs in the stacked layers are connected with the display substrate through transparent electrodes.

5 9. The display device according to any of claims 1-8, wherein electrodes of micro-LEDs in the stacked layers are led out to the display substrate through vias.

10. An electronics apparatus comprising a display device according to any of claims 1-9.

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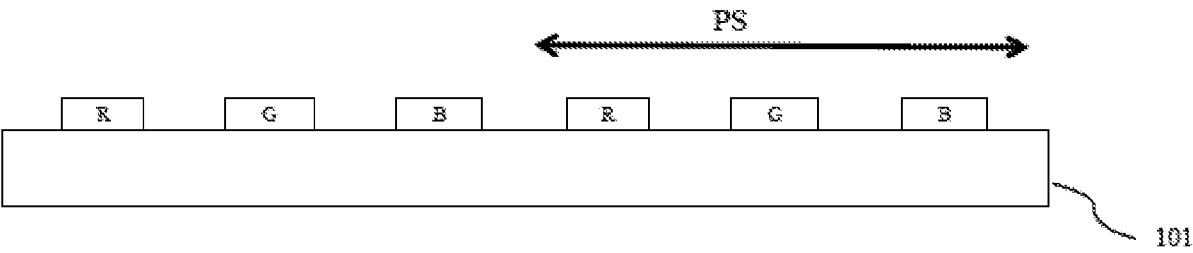


FIG. 1

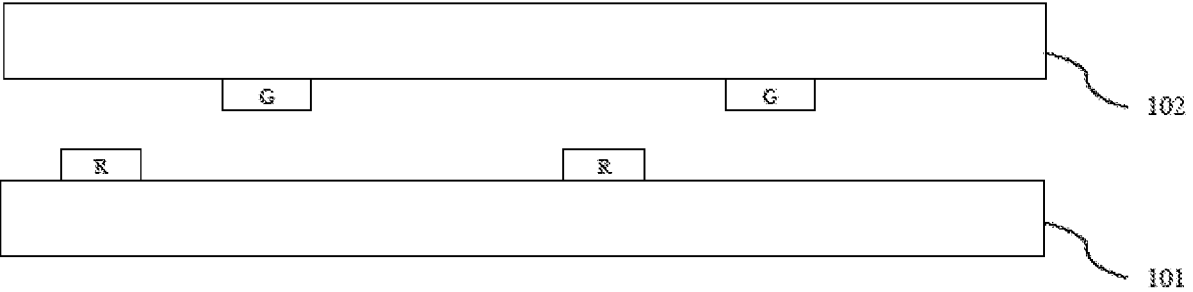


FIG. 2

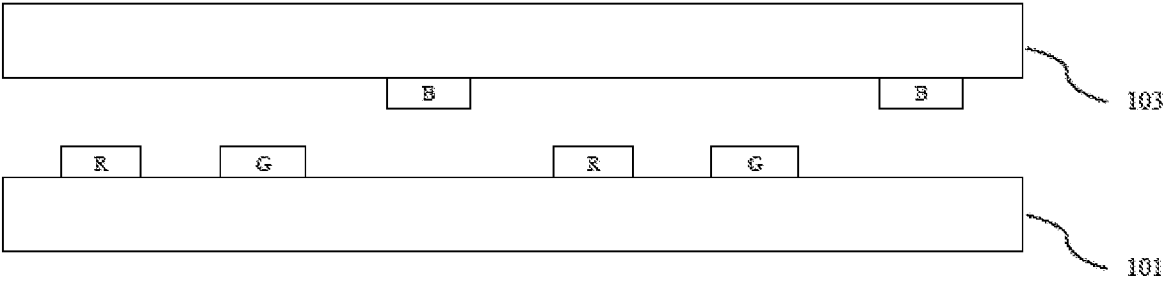


FIG. 3

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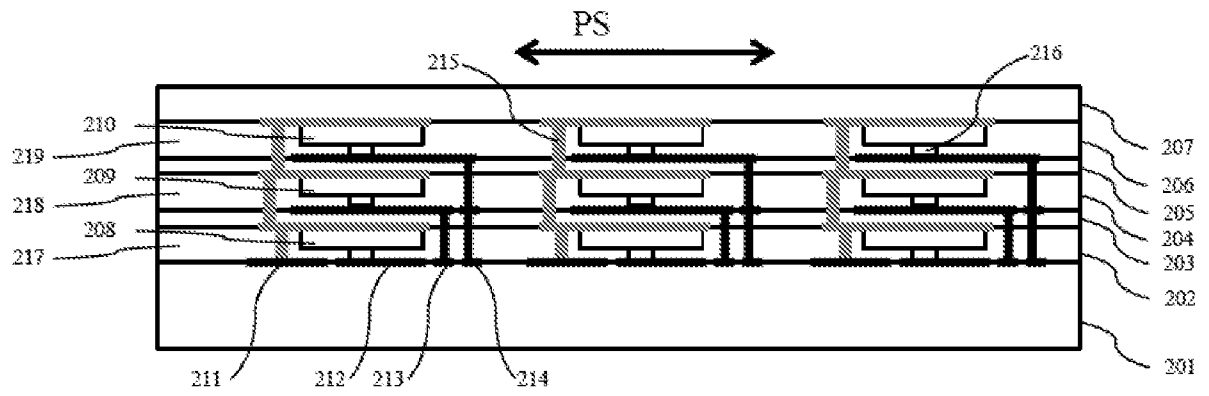


FIG. 4

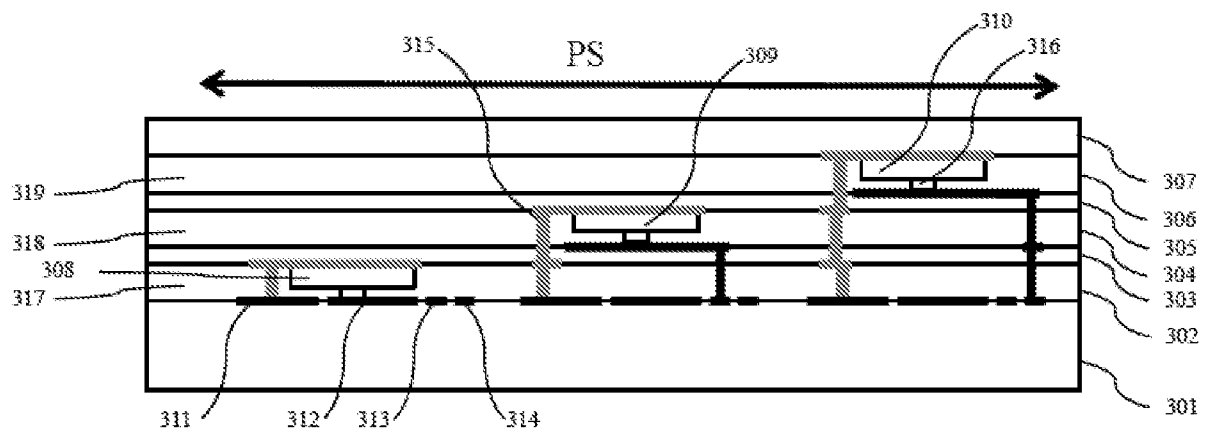


FIG. 5

INTERNATIONAL SEARCH REPORT

International application No.

PCT/CN2016/101475

A. CLASSIFICATION OF SUBJECT MATTER

H01L 27/15(2006.01)i; H01L 33/54(2010.01)i; G09F 9/33(2006.01)i

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

H01L 27/-,H01L 33/-,H01L 51/-,G09F 9/-

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

CNKI,CNPAT,WPI,EPODOC:LED,micro+ w led?,display,substrate,layer,stack+,overlap+,pile,mLED,vertical,print,transfer

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2015357315 A1 (NTHDEGREE TECHNOLOGIES WORLDWIDE INC.) 10 December 2015 (2015-12-10) description paragraphs [0079]-[0089] and figure 9	1-10
X	US 2014209936 A1 (NTHDEGREE TECHNOLOGIES WORLDWIDE INC.) 31 July 2014 (2014-07-31) description paragraphs [0037]-[0074] and figures 2-7	1-10
A	CN 104183585 A (GUANGDONG VTRON TECHNOLOGIES CO., LTD.) 03 December 2014 (2014-12-03) the whole document	1-10
A	CN 202205749 U (HAIHUA TECHNOLOGY CO., LTD.) 25 April 2012 (2012-04-25) the whole document	1-10
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☐ Further documents are listed in the continuation of Box C.☒ See patent family annex.

* Special categories of cited documents:

“A” document defining the general state of the art which is not considered to be of particular relevance

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“P” document published prior to the international filing date but later than the priority date claimed

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“X” document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone

“Y” document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art

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INTERNATIONAL SEARCH REPORT
Information on patent family members

International application No.

PCT/CN2016/101475

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